

### FEATURES

- BROAD BAND INTERNALLY MATCHED FET
- HIGH POWER  
P1dB= 39.5dBm at 9.5GHz to 10.5GHz
- HIGH GAIN  
G1dB= 6.0dB at 9.5GHz to 10.5GHz
- HERMETICALLY SEALED PACKAGE



### RF PERFORMANCE SPECIFICATIONS ( Ta= 25°C )

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Gain Compression Point	P1dB	VDS= 9V IDSSet= 4.0A f = 9.5 to 10.5GHz	dBm	38.5	39.5	—
Power Gain at 1dB Gain Compression Point	G1dB		dB	5.0	6.0	—
Drain Current	IDS		A	—	3.4	4.4
Power Added Efficiency	$\eta_{add}$		%	—	22	—
Channel Temperature Rise	$\Delta T_{ch}$		(VDS X IDSS + Pin – P1dB) X Rth(c-c)	°C	—	—

Recommended Gate Resistance(Rg): 100  $\Omega$

### ELECTRICAL CHARACTERISTICS ( Ta= 25°C )

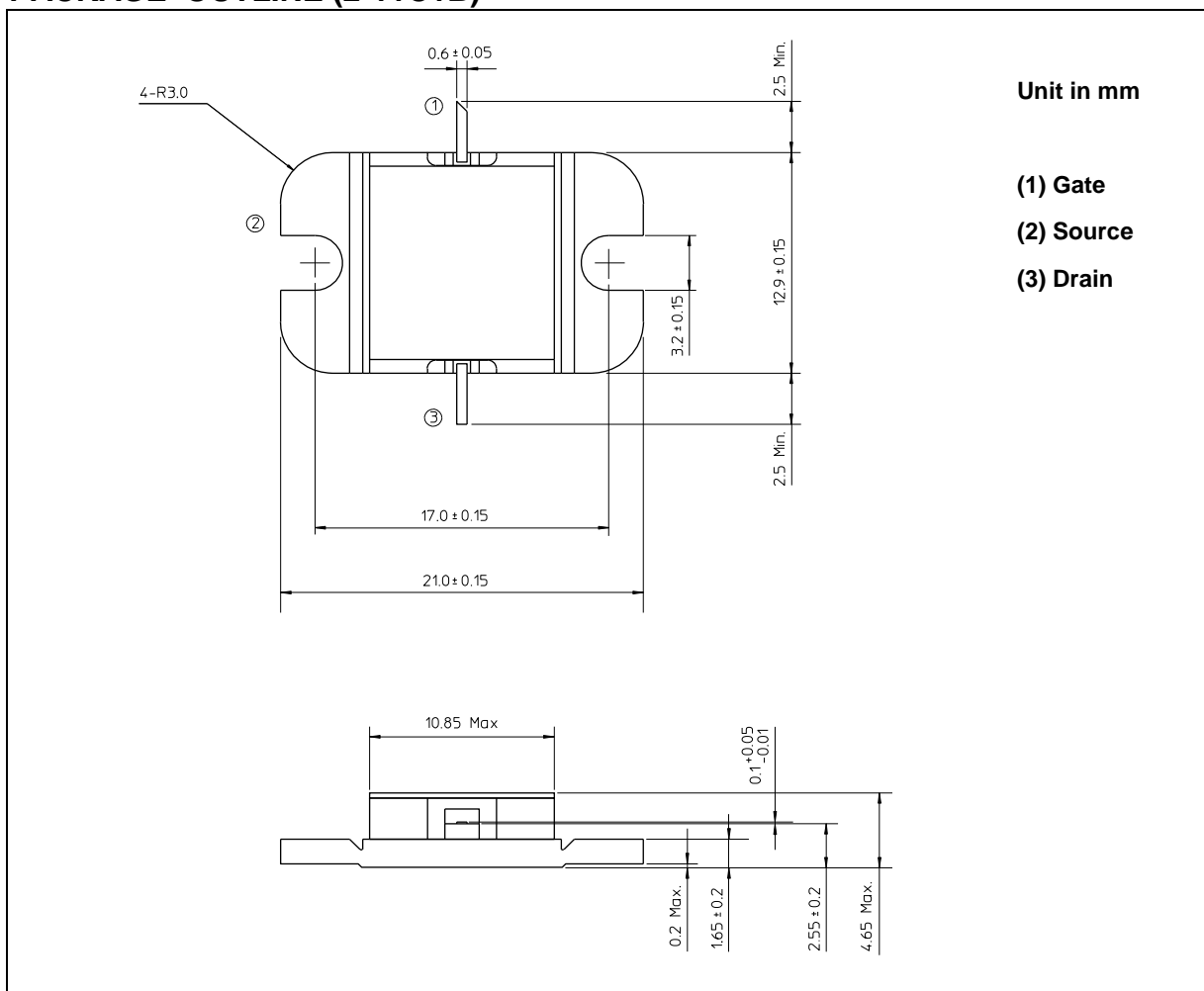
CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	VDS= 3V IDSS= 4.0A	S	—	2.4	—
Pinch-off Voltage	VGSoff	VDS= 3V IDSS= 120mA	V	-2.0	-3.5	-5.0
Saturated Drain Current	IDSS	VDS= 3V VGS= 0V	A	—	8.0	—
Gate-Source Breakdown Voltage	VGSO	IGS= -120 $\mu$ A	V	-5	—	—
Thermal Resistance	Rth(c-c)	Channel to Case	°C/W	—	1.6	2.5

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**ABSOLUTE MAXIMUM RATINGS (Ta= 25°C)**

CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	VDS	V	15
Gate-Source Voltage	VGS	V	-5
Drain Current	IDS	A	10.4
Total Power Dissipation (Tc= 25°C)	PT	W	60
Channel Temperature	Tch	°C	175
Storage	Tstg	°C	-65 to +175

**PACKAGE OUTLINE (2-11C1B)**

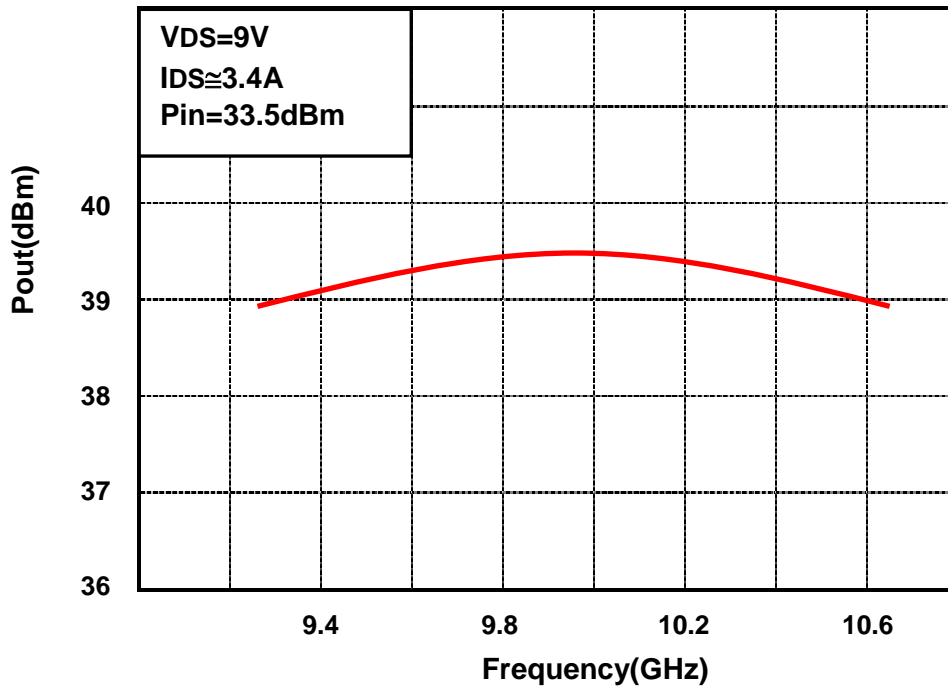


**HANDLING PRECAUTIONS FOR PACKAGE MODEL**

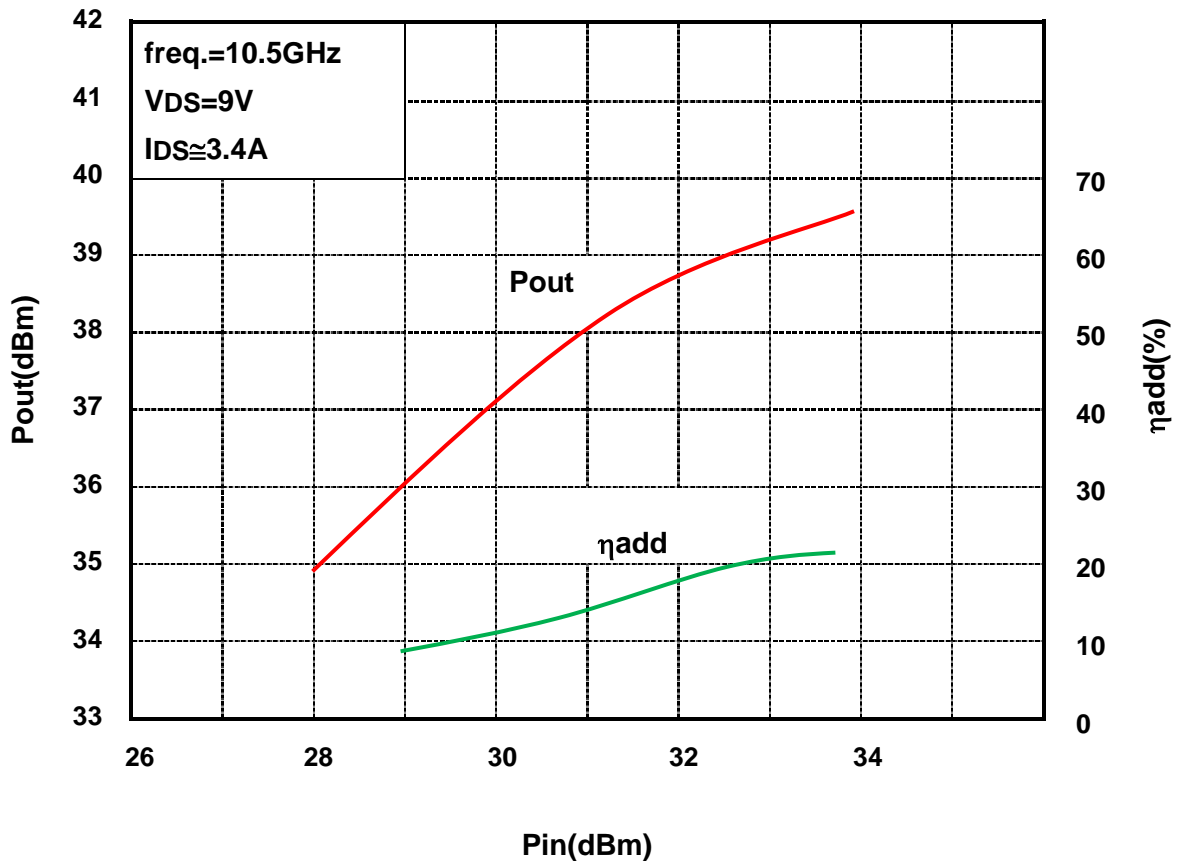
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C or 3 seconds at 350°C.

**RF PERFORMANCE**

**Output Power (Pout) vs. Frequency**



**Output Power(Pout) vs. Input Power(Pin)**



Power Dissipation(PT) vs. Case Temperature(Tc)

